

IN-PROCESS QUALITY CONTROL RECORD		YANTRAM MEDTECH PVT LTD
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Product: V TRACK

Date: _____

Done By: _____

Sr. No	Checkpoints			Acceptance Criteria	Test Method	PCB NO:	PCB NO:
	SOLDERING INSPECTION & VISUAL TEST						
1	PCB HEALTH (worn out, damage)	Solder balls	No defects have to be there.	Visual Test			
		Metal balls	No defects have to be there.	Visual Test			
		Solder Bridges	No defects have to be there.	Visual Test			
		Dry solder	No defects have to be there.	Visual Test			
2	Over soldering shorts	Open circuit	No defects have to be there.	Visual Test			
		Solder void	No defects have to be there.	Visual Test			
		Solder quality	No defects have to be there.	Visual Test			
3	OPENPADS (Pin or Pad no contact)	Lifted lead	No defects have to be there.	Visual Test			
4	Misaligned /Misplaced components.			Visual Test			
5		POGO Pins	No defects have to be there.	Visual Test			
		BUTTON	No defects have to be there.	Visual Test			

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Physical damage of components	MCU	No defects have to be there.	Visual Test				
	Regulator	No defects have to be there.	Visual Test				
	PC MOSFET	No defects have to be there.	Visual Test				
6	Component Direction & Values	U1	Placement of Component to match exactly with PCB footprint markers/Value should match the data from assembly documents/BOM	Visual Test			
		U2	Placement of Component to match exactly with PCB footprint markers/Value should match the data from assembly documents/BOM	Visual Test			
		PS1	Placement of Component to match exactly with PCB footprint markers/Value should match the data from assembly documents/BOM	Visual Test			
		IC1	Placement of Component to match exactly with PCB footprint markers/Value should match the data	Visual Test			

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			from assembly documents/BOM					
		D4	Placement of Component to match exactly with PCB footprint markers/Value should match the data from assembly documents/BOM	Visual Test				
		D2	Placement of Component to match exactly with PCB footprint markers/Value should match the data from assembly documents/BOM	Visual Test				
		D1	Placement of Component to match exactly with PCB footprint markers/Value should match the data from assembly documents/BOM	Visual Test				
		MOSFETS	Placement of Component to match exactly with PCB footprint markers/Value should match the data from assembly documents/BOM	Visual Test				
7	LEDs	POWER ON/OFF	No defects have to be there.	Visual Test				

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		BLE indication	No defects have to be there.	Visual Test				
8	SWITCHES	INTERRUPT button	No defects have to be there.	Visual Test				
	CONTINUITY TEST							
9	NOT SHORT CIRCUIT	3.3V -- Gnd	No Short Circuit	Continuity Test				
		MCU 13th & 12 th Pin	No Short Circuit	Continuity Test				
		MCU each pin with next pin	No Short Circuit	Continuity Test				
10	SHORT CIRCUIT	U1 Pin1,12,20,31	Short Circuit	Continuity Test				
		All 3.3Line	Short Circuit	Continuity Test				
		All Gnd	Short Circuit	Continuity Test				
		USB body & Gnd	Short Circuit	Continuity Test				
		Pin7 – G (SSD)	Resistance = 330Ω	Continuity Test				
		Pin8 – DP (SSD)	Resistance = 330Ω	Continuity Test				
12	OPEN CIRCUIT	Pin12 – D1 (SSD)	Open Circuit	Continuity Test				
		Pin13 – D2 (SSD)	Open Circuit	Continuity Test				
		Pin14 – D3 (SSD)	Open Circuit	Continuity Test				
		Pin15 – D4 (SSD)	Open Circuit	Continuity Test				
	ELECTRICAL TEST							

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13	BMS BLOCK	USB PIN 1 & 5	Voltage = 5V	Electrical test			
		U2 Pin 4	Voltage = 5V	Electrical test			
14	POWER SUPPLY BLOCK	Batt +ve – U2 pin3	Voltage = 3.7V	Electrical test			
		U1 Pin 13	Voltage = 3.3V	Electrical test			
		J1 Pin1	Voltage = 3.3V	Electrical test			
		JP1 Pin1	Voltage = 4.2V	Electrical test			
		IC1 Pin6 ,5	Voltage = 3.3 to 3.7V	Electrical test			
		PS1 Pin1	Voltage = 3.3 to 3.7V	Electrical test			
	Functionality Test						
15	S/W Version	V TRACK					
16	Power	Power On/Off	1.Normal Press and Release – Power On 2.Long press(4sec) – Power Off	Functionalit y Test			
17	SWITCHES	Interrupt	Device wake up from Deep Sleep	By pressing the Power/Mod e button			
18	LEDs	Charging LED	LED ON – Charging LED OFF – Full charge	Functional Visual test (By plug in to the charger)			
		BLE LED	Ble Mode – Blinks for 3 times	Functional Visual test			

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			Beacon Mode --One blink					
19	BLE	Configuration	Device Configure with Mobile app	Functionalit y test				
		Data transmission	Data communication between Mobile app and device	Functionalit y test				
		App security	App is not interrupted by any other third party app.	Functionalit y test				
20	Battery	Battery percentage	Observe the Battery percentage in mobile app	Functionalit y test				
21	Charger	Charge detection	Observe the mobile is charging or not, while charging device is turned off automatically	Functionalit y test				
22	RTC	RTC timestamp	Observe the timestamp – device time is syncing with NTP time.	Functionalit y test				
23	EEPROM	EEPROM	Observe the EEPROM data is replicated in mobile app after successful reconnection with Mobile app.	Functionalit y test				